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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	185000
Number of Logic Elements/Cells	490000
Total RAM Bits	46080000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxea5n3f40i4n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering (1), (2), (3) (Part 2 of 2)

Transceiver Speed	Core Speed Grade										
Grade	C1	C2, C2L	C3	C4	12, 12L	13, 13L	I3YY	14			
3 GX channel—8.5 Gbps	_	Yes	Yes	Yes	_	Yes	Yes ⁽⁴⁾	Yes			

Notes to Table 1:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.
- (3) C2L, I2L, and I3L speed grades are for low-power devices.
- (4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering (1), (2)

Transacius Snood Crada	Core Speed Grade								
Transceiver Speed Grade	C1	C2	12	13					
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	_	_					
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes					

Notes to Table 2:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)

Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Power supply for core voltage and periphery circuitry	-0.5	1.35	V
V _{CCPT}	Power supply for programmable power technology	-0.5	1.8	V
V _{CCPGM}	Power supply for configuration pins	-0.5	3.9	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	-0.5	3.4	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	-0.5	3.9	V
V _{CCPD}	I/O pre-driver power supply	-0.5	3.9	V
V _{CCIO}	I/O power supply	-0.5	3.9	V

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Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
t _{RAMP} P	Power supply ramp time	Standard POR	200 μs	_	100 ms	_
	Power supply railly tillle	Fast POR	200 μs	_	4 ms	_

Notes to Table 6:

- (1) V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V.
- (2) If you do not use the design security feature in Stratix V devices, connect V_{CCBAT} to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V_{CCBAT}. Stratix V devices will not exit POR if V_{CCBAT} stays at logic low.
- (3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.
- (4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit	
V _{CCA_GXBL}	Transceiver channel PLL power supply (left	GX, GS, GT	2.85	3.0	3.15	V	
(1), (3)	side)	७४, ७७, ७१	2.375	2.5	2.625	V	
V _{CCA_GXBR}	Transceiver channel PLL power supply (right	GX, GS	2.85	3.0	3.15	V	
$(1), (\overline{3})$	side)	রম, রহ	2.375	2.5	2.625	V	
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V	
	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V _{CCHIP_L}	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V_{CCHIP_R}	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V _{CCHSSI_L}	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V _{CCHSSI_R}	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
			0.82	0.85	0.88		
V _{CCR_GXBL}	Receiver analog power supply (left side)	CV CC CT	0.87	0.90	0.93	V	
(2)	Treceiver arialog power supply (left side)) GX, GS, GT	0.97	1.0	1.03	v	
			1.03	1.05	1.07	1	

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Table 8 shows the transceiver power supply voltage requirements for various conditions.

Table 8. Transceiver Power Supply Voltage Requirements

Conditions	Core Speed Grade	VCCR_GXB & VCCT_GXB (2)	VCCA_GXB	VCCH_GXB	Unit
If BOTH of the following conditions are true:					
■ Data rate > 10.3 Gbps.	All	1.05			
■ DFE is used.					
If ANY of the following conditions are true ⁽¹⁾ :			3.0		
ATX PLL is used.					
■ Data rate > 6.5Gbps.	All	1.0			
■ DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used.				1.5	V
If ALL of the following	C1, C2, I2, and I3YY	0.90	2.5		
conditions are true: ATX PLL is not used.					
■ Data rate ≤ 6.5Gbps.	C2L, C3, C4, I2L, I3, I3L, and I4	0.85	2.5		
DFE, AEQ, and EyeQ are not used.					

Notes to Table 8:

- (1) Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.
- (2) If the VCCR_GXB and VCCT_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR_GXB and VCCT_GXB are set to either 0.90 V or 0.85 V, they can be shared with the VCC core supply.

DC Characteristics

This section lists the supply current, I/O pin leakage current, input pin capacitance, on-chip termination tolerance, and hot socketing specifications.

Supply Current

Supply current is the current drawn from the respective power rails used for power budgeting. Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

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Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 2 of 2)

I/O				V _{DIF(DC)} (V)		V _{X(AC)} (V)				V _{CM(DC)} (V	V _{DIF(AC)} (V)		
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCIO} + 0.3	_	0.5* V _{CCIO}	_	0.4* V _{CCIO}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.3	V _{CCIO} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5*V _{CCIO} - 0.12	0.5* V _{CCIO}	0.5*V _{CCIO} + 0.12	0.4* V _{CCIO}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.44	0.44

Table 22. Differential I/O Standard Specifications for Stratix V Devices (7)

I/O	Vc	_{CIO} (V)	(10)		V _{ID} (mV) ⁽⁸⁾			$V_{ICM(DC)}$ (V)		V _o	_D (V) (6)	V_{OCM} (V) (6)		
Standard	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max
PCML	Trar	Transmitter, receiver, and input reference clock pins of the high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to Table 23 on page 18.													
2.5 V	2.375	2.5	2.625	100	V _{CM} =	_	0.05	D _{MAX} ≤ 700 Mbps	1.8	0.247	_	0.6	1.125	1.25	1.375
LVDS (1)	2.373	2.3	2.023	100	1.25 V		1.05	D _{MAX} > 700 Mbps	1.55	0.247	_	0.6	1.125	1.25	1.375
BLVDS (5)	2.375	2.5	2.625	100	_	_	_	_	_	_	_	_	_	_	_
RSDS (HIO) ⁽²⁾	2.375	2.5	2.625	100	V _{CM} = 1.25 V	_	0.3	_	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini- LVDS (HIO) (3)	2.375	2.5	2.625	200	_	600	0.4	_	1.325	0.25	_	0.6	1	1.2	1.4
LVPECL (4	_	_	_	300	_	_	0.6	D _{MAX} ≤ 700 Mbps	1.8	_	_	_	_	_	_
), (9)	_	_	_	300	_	_	1	D _{MAX} > 700 Mbps	1.6	_	_	_	_	_	_

Notes to Table 22:

- (1) For optimized LVDS receiver performance, the receiver voltage input range must be between 1.0 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.
- (2) For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.
- (3) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.
- (4) For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.
- (5) There are no fixed V_{ICM} , V_{OD} , and V_{OCM} specifications for BLVDS. They depend on the system topology.
- (6) RL range: $90 \le RL \le 110 \Omega$.
- (7) The 1.4-V and 1.5-V PCML transceiver I/O standard specifications are described in "Transceiver Performance Specifications" on page 18.
- (8) The minimum VID value is applicable over the entire common mode range, VCM.
- (9) LVPECL is only supported on dedicated clock input pins.
- (10) Differential inputs are powered by VCCPD which requires 2.5 $\rm V.$

Power Consumption

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus[®] II PowerPlay Power Analyzer feature.

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices $^{(1)}$ (Part 3 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trar	sceive Grade	er Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Reconfiguration clock (mgmt_clk_clk) frequency	_	100	_	125	100	_	125	100	_	125	MHz
Receiver											
Supported I/O Standards	_			1.4-V PCMI	L, 1.5-V	PCML,	2.5-V PCM	L, LVPE	CL, and	d LVDS	
Data rate (Standard PCS)	_	600	_	12200	600	_	12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS) (9), (23)	_	600	_	14100	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
Absolute V _{MAX} for a receiver pin ⁽⁵⁾	_	_	_	1.2	_	_	1.2	_	_	1.2	V
Absolute V _{MIN} for a receiver pin	_	-0.4	_	_	-0.4	_	_	-0.4	_	_	V
Maximum peak- to-peak differential input voltage V _{ID} (diff p- p) before device configuration (22)	_	_	_	1.6	_	_	1.6	_	_	1.6	V
Maximum peak-	$V_{CCR_GXB} = 1.0 \text{ V}/1.05 \text{ V} $ $(V_{ICM} = 0.70 \text{ V})$	_	_	2.0	_	_	2.0	_	_	2.0	V
differential input voltage V _{ID} (diff p- p) after device configuration (18),	$V_{CCR_GXB} = 0.90 \text{ V}$ $(V_{ICM} = 0.6 \text{ V})$		_	2.4	_	_	2.4	_	_	2.4	V
(22)	$V_{CCR_GXB} = 0.85 \text{ V}$ $(V_{ICM} = 0.6 \text{ V})$	_	_	2.4	_	_	2.4	_	_	2.4	V
Minimum differential eye opening at receiver serial input pins (6), (22), (27)	_	85	_	_	85	_	_	85	_	_	mV

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 5 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	sceive Grade	r Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	DC Gain Setting = 0		0	_	_	0		_	0	_	dB
	DC Gain Setting = 1		2	_	_	2		_	2	_	dB
Programmable DC gain	DC Gain Setting = 2		4	_		4	_	_	4	_	dB
	DC Gain Setting = 3	_	6	_	_	6	_	_	6	_	dB
	DC Gain Setting = 4	_	8	_	_	8	_	_	8	_	dB
Transmitter											
Supported I/O Standards	_				-	1.4-V an	ıd 1.5-V PC	ML			
Data rate (Standard PCS)	_	600	_	12200	600	_	12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS)	_	600	_	14100	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
	85- Ω setting		85 ± 20%	_	_	85 ± 20%	_	_	85 ± 20%	_	Ω
Differential on-	100-Ω setting		100 ± 20%	_	_	100 ± 20%	_	_	100 ± 20%	_	Ω
chip termination resistors	120-Ω setting	_	120 ± 20%	_	_	120 ± 20%	_	_	120 ± 20%	_	Ω
	150-Ω setting		150 ± 20%	_	_	150 ± 20%	_	_	150 ± 20%	_	Ω
V _{OCM} (AC coupled)	0.65-V setting	_	650	_	_	650	_	_	650	_	mV
V _{OCM} (DC coupled)	_		650	_	_	650	_	_	650	_	mV
Rise time (7)	20% to 80%	30	_	160	30	_	160	30	_	160	ps
Fall time ⁽⁷⁾	80% to 20%	30	_	160	30	_	160	30		160	ps
Intra-differential pair skew	Tx V _{CM} = 0.5 V and slew rate of 15 ps	_	_	15	_	_	15	_	_	15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode	_	_	120	_	_	120	_	_	120	ps

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Table 26 shows the approximate maximum data rate using the 10G PCS.

Table 26. Stratix V 10G PCS Approximate Maximum Data Rate (1)

Mode ⁽²⁾	Transceiver	PMA Width	64	40	40	40	32	32		
Widue (2)	Speed Grade	PCS Width	64	66/67	50	40	64/66/67	32		
	1	C1, C2, C2L, I2, I2L core speed grade	14.1	14.1	10.69	14.1	13.6	13.6		
	2	C1, C2, C2L, I2, I2L core speed grade	12.5	12.5	10.69	12.5	12.5	12.5		
	2	C3, I3, I3L core speed grade	12.5	12.5	10.69	12.5	10.88	10.88		
FIFO or Register	3	C1, C2, C2L, I2, I2L core speed grade								
		C3, I3, I3L core speed grade	8.5 Gbps							
		C4, I4 core speed grade								
		I3YY core speed grade	10.3125 Gbps							

Notes to Table 26:

⁽¹⁾ The maximum data rate is in Gbps.

⁽²⁾ The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5) $^{(1)}$

Symbol/	Conditions	S	Transceive Speed Grade			Transceive peed Grade		Unit		
Description		Min	Тур	Max	Min	Тур	Max	5		
Reference Clock	l		<u>I</u>	U.			<u>I</u>	<u>I</u>		
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCN	1.2-V PCML, 1.4-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LVD and HCSL							
otandardo	RX reference clock pin	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS								
Input Reference Clock Frequency (CMU PLL) ⁽⁶⁾	_	40	_	710	40	_	710	MHz		
Input Reference Clock Frequency (ATX PLL) (6)	_	100	_	710	100	_	710	MHz		
Rise time	20% to 80%	_	_	400	_	_	400			
Fall time	80% to 20%	_	_	400	_	<u> </u>	400	ps		
Duty cycle	_	45	_	55	45	_	55	%		
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	_	33	30	_	33	kHz		
Spread-spectrum downspread	PCle		0 to -0.5	_	_	0 to -0.5	_	%		
On-chip termination resistors (19)	_	_	100	_	_	100	_	Ω		
Absolute V _{MAX} (3)	Dedicated reference clock pin	_	_	1.6	_	_	1.6	V		
	RX reference clock pin	_	_	1.2	_	_	1.2			
Absolute V _{MIN}	_	-0.4	_	_	-0.4		_	V		
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	mV		
V _{ICM} (AC coupled)	Dedicated reference clock pin		1050/1000	2)	1	050/1000	2)	mV		
	RX reference clock pin	1	.0/0.9/0.85	(22)	1.	V				
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	mV		

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5) $^{(1)}$

Symbol/	Conditions		Transceiver Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Differential on-chip termination resistors (7)	GT channels	_	100	_	_	100	_	Ω
	85-Ω setting	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-chip termination resistors	100-Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	Ω
for GX channels (19)	120-Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150-Ω setting	_	150 ± 30%	_	_	150 ± 30%	_	Ω
V _{ICM} (AC coupled)	GT channels	_	650	_	_	650	_	mV
	VCCR_GXB = 0.85 V or 0.9 V	_	600	_	_	600	_	mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 1.0 V full bandwidth	_	700	_	_	700	_	mV
	VCCR_GXB = 1.0 V half bandwidth	_	750	_	_	750	_	mV
t _{LTR} ⁽⁹⁾	_	_	_	10	_	_	10	μs
t _{LTD} ⁽¹⁰⁾	_	4	_	_	4	_	_	μs
t _{LTD_manual} (11)		4	_	_	4	_	_	μs
t _{LTR_LTD_manual} (12)		15	_	_	15	_	_	μs
Run Length	GT channels	_	_	72	_	_	72	CID
nuii Leiigiii	GX channels				(8)			
CDR PPM	GT channels	_	_	1000	_	_	1000	± PPM
ODITITIVI	GX channels				(8)			
Programmable	GT channels	_	_	14	_	_	14	dB
equalization (AC Gain) ⁽⁵⁾	GX channels				(8)			
Programmable	GT channels	_	_	7.5	_	_	7.5	dB
DC gain ⁽⁶⁾	GX channels				(8)			
Differential on-chip termination resistors ⁽⁷⁾	GT channels		100	_	_	100	_	Ω
Transmitter	· '		•			•	•	
Supported I/O Standards	_	1.4-V and 1.5-V PCML						
Data rate (Standard PCS)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS)	GX channels	600	_	12,500	600		12,500	Mbps

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 4 of 5) $^{(1)}$

Symbol/	Conditions		Transceive peed Grade			Transceive Deed Grade		Unit	
Description		Min	Тур	Max	Min	Тур	Max		
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps	
Differential on-chip	GT channels	_	100	_		100	<u> </u>	Ω	
termination resistors	GX channels			•	(8)		<u>'</u>		
\/	GT channels	_	500	_	_	500	_	mV	
V _{OCM} (AC coupled)	GX channels			•	(8)		<u>'</u>		
Diag/Fall time	GT channels	_	15	_	_	15	_	ps	
Rise/Fall time	GX channels		<u>I</u>		(8)				
Intra-differential pair skew	GX channels		(8)						
Intra-transceiver block transmitter channel-to- channel skew	GX channels				(8)				
Inter-transceiver block transmitter channel-to- channel skew	GX channels				(8)				
CMU PLL									
Supported Data Range	_	600	_	12500	600	_	8500	Mbps	
t _{pll_powerdown} (13)	_	1	_	_	1	_	_	μs	
t _{pll_lock} (14)	_	_	_	10	_	_	10	μs	
ATX PLL									
	VCO post- divider L=2	8000	_	12500	8000	_	8500	Mbps	
	L=4	4000	_	6600	4000	_	6600	Mbps	
Supported Data Rate	L=8	2000	_	3300	2000	_	3300	Mbps	
Range for GX Channels	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000	_	1762.5	Mbps	
Supported Data Rate Range for GT Channels	VCO post- divider L=2	9800	_	14025	9800	_	12890	Mbps	
t _{pll_powerdown} (13)	_	1	_	_	1	_	_	μs	
t _{pll_lock} (14)	_	_	_	10	_	_	10	μs	
fPLL			•						
Supported Data Range	_	600	_	3250/ 3.125 ⁽²³⁾	600	_	3250/ 3.125 ⁽²³⁾	Mbps	
t _{pll_powerdown} (13)	_	1	_	_	1	_	_	μs	

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Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)

		Peformance							
Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit	
		Modes us	ing Three	DSPs	•				
One complex 18 x 25	425	425	415	340	340	275	265	MHz	
Modes using Four DSPs									
One complex 27 x 27	465	465	465	380	380	300	290	MHz	

Memory Block Specifications

Table 33 lists the Stratix V memory block specifications.

Table 33. Memory Block Performance Specifications for Stratix V Devices (1), (2) (Part 1 of 2)

		Resources Used		Performance							
Memory	Mode	ALUTS	Memory	C 1	C2, C2L	C 3	C4	12, I2L	13, 13L, 13YY	14	Unit
	Single port, all supported widths	0	1	450	450	400	315	450	400	315	MHz
MLAB	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	MHz
IVILAD	Simple dual-port, x16 depth (3)	0	1	675	675	533	400	675	533	400	MHz
	ROM, all supported widths	0	1	600	600	500	450	600	500	450	MHz

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Periphery Performance

This section describes periphery performance, including high-speed I/O and external memory interface.

I/O performance supports several system interfaces, such as the **LVDS** high-speed I/O interface, external memory interface, and the **PCI/PCI-X** bus interface. General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-**LVTTL/LVCMOS** are capable of a typical 167 MHz and 1.2-**LVCMOS** at 100 MHz interfacing frequency with a 10 pF load.



The actual achievable frequency depends on design- and system-specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

High-Speed I/O Specification

Table 36 lists high-speed I/O timing for Stratix V devices.

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 1 of 4)

_														
Cumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	13, I3L	., I3YY		C4,I	4	Unit
Symbol	Conuntions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{HSCLK_in} (input clock frequency) True Differential I/O Standards	Clock boost factor W = 1 to 40 (4)	5		800	5	_	800	5		625	5		525	MHz
f _{HSCLK_in} (input clock frequency) Single Ended I/O Standards (3)	Clock boost factor W = 1 to 40 (4)	5		800	5	_	800	5		625	5		525	MHz
f _{HSCLK_in} (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 (4)	5		520	5	_	520	5		420	5		420	MHz
f _{HSCLK_OUT} (output clock frequency)	_	5		800	5	_	800	5		625 (5)	5		525 (5)	MHz

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Table 49. DCLK-to-DATA[] Ratio (1) (Part 2 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
FPP ×32	Enabled	Disabled	8
	Enabled	Enabled	8

Note to Table 49:

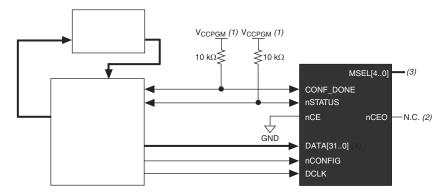
(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.



If the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio -1) clock cycles after the last data is latched into the Stratix V device.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host



Notes to Figure 11:

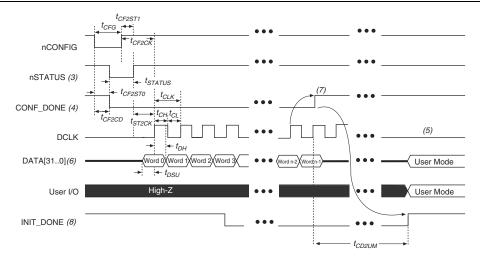
- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V_{CCPGM} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V_{CCPGM}.
- (2) You can leave the nceo pin unconnected or use it as a user I/O pin when it does not feed another device's nce pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP $\times 8$, use DATA [7..0]. If you use FPP $\times 16$, use DATA [15..0].

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FPP Configuration Timing when DCLK-to-DATA [] = 1

Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA[] ratio is 1.

Figure 12. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1 (1), (2)



Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA[] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP ×16, use DATA [15..0]. For FPP ×8, use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the <code>INIT_DONE</code> pin is configured into the device, the <code>INIT_DONE</code> goes low.

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Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is 1.

Table 50. FPP Timing Parameters for Stratix V Devices (1)

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	_	600	ns
t _{CF2ST0}	nconfig low to nstatus low	_	600	ns
t _{CFG}	nCONFIG low pulse width	2	_	μS
t _{STATUS}	nstatus low pulse width	268	1,506 ⁽²⁾	μ\$
t _{CF2ST1}	nCONFIG high to nSTATUS high	_	1,506 ⁽³⁾	μ\$
t _{CF2CK} (6)	nCONFIG high to first rising edge on DCLK	1,506	_	μ\$
t _{ST2CK} (6)	nSTATUS high to first rising edge of DCLK	2	_	μ\$
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	0	_	ns
t _{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t _{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	_	100	MHz
t _{CD2UM}	CONF_DONE high to user mode (4)	175	437	μS
+	GOVER DOVER high to GUVERN anabled	4 × maximum		
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (8576 × CLKUSR period) ⁽⁵⁾	_	_

Notes to Table 50:

- (1) Use these timing parameters when the decompression and design security features are disabled.
- (2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) This value is applicable if you do not delay configuration by externally holding the nstatus low.
- (4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.
- (5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is more than 1.

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Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [] ratio is more than 1.

Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1 $^{(1)}$

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nconfig low to conf_done low	_	600	ns
t _{CF2ST0}	nconfig low to nstatus low	_	600	ns
t _{CFG}	nCONFIG low pulse width	2	_	μS
t _{STATUS}	nstatus low pulse width	268	1,506 ⁽²⁾	μS
t _{CF2ST1}	nconfig high to nstatus high	_	1,506 ⁽²⁾	μS
t _{CF2CK} (5)	nconfig high to first rising edge on DCLK	1,506	_	μS
t _{ST2CK} (5)	nstatus high to first rising edge of DCLK	2	_	μS
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	N-1/f _{DCLK} ⁽⁵⁾	_	S
t _{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t _{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	_	100	MHz
t _R	Input rise time	_	40	ns
t _F	Input fall time	_	40	ns
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (8576 × CLKUSR period) ⁽⁴⁾	_	_

Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nconfig or nstatus low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (5) N is the DCLK-to-DATA ratio and f_{DCLK} is the DCLK frequency the system is operating.
- (6) If nstatus is monitored, follow the t_{status} specification. If nstatus is not monitored, follow the t_{cfack} specification.

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Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$\begin{array}{c} t_{\text{CD2CU}} + (8576 \times \\ \text{CLKUSR period}) \end{array}$	_	_

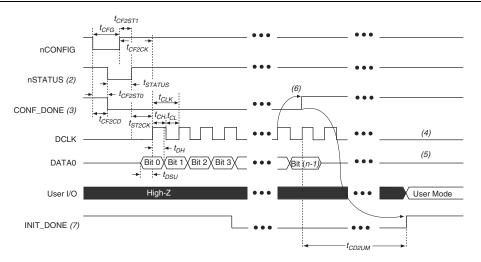
Notes to Table 53:

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- $(2) \quad t_{\text{CF2CD}}, t_{\text{CF2ST0}}, t_{\text{CFG}}, t_{\text{STATUS}}, \text{ and } t_{\text{CF2ST1}} \text{ timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63}.$
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform (1)



Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

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Table 54 lists the PS configuration timing parameters for Stratix V devices.

Table 54. PS Timing Parameters for Stratix V Devices

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	_	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	_	600	ns
t _{CFG}	nCONFIG low pulse width	2		μS
t _{STATUS}	nstatus low pulse width	268	1,506 ⁽¹⁾	μS
t _{CF2ST1}	nCONFIG high to nSTATUS high	_	1,506 ⁽²⁾	μS
t _{CF2CK} (5)	nCONFIG high to first rising edge on DCLK	1,506		μS
t _{ST2CK} (5)	nstatus high to first rising edge of DCLK	2	_	μS
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	0		ns
t _{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t _{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t _{CLK}	DCLK period	1/f _{MAX}		S
f _{MAX}	DCLK frequency	_	125	MHz
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (8576 × CLKUSR period) (4)	_	_

Notes to Table 54:

- (1) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (2) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.
- (3) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section.
- (5) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

Initialization

Table 55 lists the initialization clock source option, the applicable configuration schemes, and the maximum frequency.

Table 55. Initialization Clock Source Option and the Maximum Frequency

Initialization Clock Source	Configuration Schemes	Maximum Frequency	Minimum Number of Clock Cycles ⁽¹⁾
Internal Oscillator	AS, PS, FPP	12.5 MHz	
CLKUSR	AS, PS, FPP (2)	125 MHz	8576
DCLK	PS, FPP	125 MHz	

Notes to Table 55:

- $(1) \quad \text{The minimum number of clock cycles required for device initialization}.$
- (2) To enable CLKUSR as the initialization clock source, turn on the Enable user-supplied start-up clock (CLKUSR) option in the Quartus II software from the General panel of the Device and Pin Options dialog box.

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Document Revision History

Table 61 lists the revision history for this chapter.

Table 61. Document Revision History (Part 1 of 3)

Date	Version	Changes
June 2018	3.9	■ Added the "Stratix V Device Overshoot Duration" figure.
April 2017	3.8	■ Added a footnote to the "High-Speed I/O Specifications for Stratix V Devices" table.
		■ Changed the minimum value for t _{CD2UMC} in the "PS Timing Parameters for Stratix V Devices" table.
		■ Changed the condition for 100-Ω R _D in the "OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices" table.
		■ Changed the minimum value for t _{CD2UMC} in the "AS Timing Parameters for AS '1 and AS '4 Configurations in Stratix V Devices" table
		■ Changed the minimum value for t _{CD2UMC} in the "FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1" table.
		■ Changed the minimum value for t _{CD2UMC} in the "FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1" table.
		■ Changed the minimum number of clock cycles value in the "Initialization Clock Source Option and the Maximum Frequency" table.
June 2016	3.7	■ Added the V _{ID} minimum specification for LVPECL in the "Differential I/O Standard Specifications for Stratix V Devices" table
		■ Added the I _{OUT} specification to the "Absolute Maximum Ratings for Stratix V Devices" table.
December 2015	3.6	■ Added a footnote to the "High-Speed I/O Specifications for Stratix V Devices" table.
December 2015	3.5	■ Changed the transmitter, receiver, and ATX PLL data rate specifications in the "Transceiver Specifications for Stratix V GX and GS Devices" table.
		■ Changed the configuration .rbf sizes in the "Uncompressed .rbf Sizes for Stratix V Devices" table.
July 2015	3.4	■ Changed the data rate specification for transceiver speed grade 3 in the following tables:
		"Transceiver Specifications for Stratix V GX and GS Devices"
		■ "Stratix V Standard PCS Approximate Maximum Date Rate"
		■ "Stratix V 10G PCS Approximate Maximum Data Rate"
		■ Changed the conditions for reference clock rise and fall time, and added a note to the "Transceiver Specifications for Stratix V GX and GS Devices" table.
		■ Added a note to the "Minimum differential eye opening at receiver serial input pins" specification in the "Transceiver Specifications for Stratix V GX and GS Devices" table.
		■ Changed the t _{CO} maximum value in the "AS Timing Parameters for AS '1 and AS '4 Configurations in Stratix V Devices" table.
		■ Removed the CDR ppm tolerance specification from the "Transceiver Specifications for Stratix V GX and GS Devices" table.

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Table 61. Document Revision History (Part 3 of 3)

■ Updated Table 2, Table 6, Table 7, Table 20, Table 23, Table 27, Table 47, Table 2013 2.7 ■ Added Table 24, Table 48 ■ Updated Figure 9, Figure 10, Figure 11, Figure 12 ■ Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 46 ■ Updated "Maximum Allowed Overshoot and Undershoot Voltage" ■ Updated "Maximum Allowed Overshoot and Undershoot Voltage" ■ Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, TaTable 30, Table 32, Table 35 ■ Added Table 33 ■ Added "Fast Passive Parallel Configuration Timing" ■ Added "Added "Passive Serial Configuration Timing" ■ Added "Passive Serial Configuration Timing" ■ Added "Remote System Upgrades" ■ Added "Initialization" ■ Added "Initialization" ■ Added "Raw Binary File Size" ■ Added Figure 1, Figure 2, and Figure 3. ■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 40, Table 4 Table 56, and Table 59. ■ Various edits throughout to fix bugs.	
December 2012 2.5 December 2012 D	able 60
December 2012 2.6 Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 46 Updated "Maximum Allowed Overshoot and Undershoot Voltage" Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Tatable 30, Table 32, Table 35 Added Table 33 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Raw Binary File Size" Added "Raw Binary File Size" Added Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
Table 46 Updated "Maximum Allowed Overshoot and Undershoot Voltage" Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Ta Table 30, Table 32, Table 35 Added Table 33 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 40, Table 40, Table 40, Table 56, and Table 59.	
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December 2012 2.5 Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Table 30, Table 32, Table 35 Added Table 33 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 7, Table 30, Table 31, Table 32, Table 38, Table 39, Table 40, Table 4, Table 56, and Table 59.	
Table 30, Table 35 Added Table 33 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 7 Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59. 	able 27,
December 2012 Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
December 2012 2.5 Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
 Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59. 	
 Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59. 	
■ Added "Initialization" ■ Added "Raw Binary File Size" ■ Added Figure 1, Figure 2, and Figure 3. ■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
■ Added "Raw Binary File Size" ■ Added Figure 1, Figure 2, and Figure 3. ■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
June 2012 Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 36, Table 36, Table 37, Table 38, Table 39, Table 40, Table 40, Table 56, and Table 59.	
June 2012 Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
Table 30, Table 31, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
■ Changed title of document to <i>Stratix V Device Datasheet</i> .	
■ Removed document from the Stratix V handbook and made it a separate document	cument.
February 2012 2.3 Updated Table 1–22, Table 1–29, Table 1–31, and Table 1–31.	
December 2011 2.2 ■ Added Table 2–31.	
■ Updated Table 2–28 and Table 2–34.	
■ Added Table 2–2 and Table 2–21 and updated Table 2–5 with information at Stratix V GT devices.	out
November 2011 2.1 Updated Table 2–11, Table 2–13, Table 2–20, and Table 2–25.	
■ Various edits throughout to fix SPRs.	
■ Updated Table 2–4, Table 2–18, Table 2–19, Table 2–21, Table 2–22, Table 2 Table 2–24.	2–23, and
May 2011 2.0 ■ Updated the "DQ Logic Block and Memory Output Clock Jitter Specifications	s" title.
■ Chapter moved to Volume 1.	
■ Minor text edits.	
■ Updated Table 1–2, Table 1–4, Table 1–19, and Table 1–23.	
December 2010 1.1 Converted chapter to the new template.	
■ Minor text edits.	
July 2010 1.0 Initial release.	